IN THE CLAIMS:

Please cancel 4, 10, 14, 19, 25, 38, and 45 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claims 2 and 5 and add new claims 46-51 as follows:

LISTING OF CURRENT CLAIMS

Claim 1. (Canceled)

2. (Currently Amended) A heat conductivity and brightness enhancing structure for light-emitting diode comprising: a bracket having:

a) a cathode leg support;

b) a bowl formed in an upper end of the cathode leg support;

c) a light-emitting chip located in the bowl; and

d) at least one depression formed in a bottommost section of the bowl and receiving an adhesive therein, the at least one depression having an opening directed toward the chip, the opening having a diameter smaller than a bottom face of the chip, the adhesive filling the at least one depression and adhering the chip in the bowl,

wherein a column hole is formed through the cathode leg support from at least one depression of the bowl to an outer side of the bracket.

3. (Previously Presented) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 32, wherein a column blind hole is formed in the cathode leg support from a portion below at least one depression of the bowl by a certain thickness to an outer side of the leg support.

Claim 4. (Canceled)

5. (Currently Amended) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the bowl has a recessed face having at least one step.

Claims 6-7. (Canceled)

8. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the circumference of the depression of the bowl is formed with concentric recesses.

Claims 9-11. (Canceled)

12. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein at least one of the cathode leg support and anode leg support of the bracket is formed with heat-radiating wings.

Claims 13-16. (Canceled)

17. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the bottom face of the bracket is entirely attached to a conductive metal film of a PC board.

Claims 18-22. (Canceled)

23. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board.

Claims 24-29. (Canceled)

30. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 23, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board and partially suspended.

Claim 31. (Canceled)

32. (Previously Presented) A heat conductivity and brightness enhancing structure for light-emitting diode comprising: a bracket having:

a) a cathode leg support;

b) a bowl formed in an upper end of the cathode leg support;

c) a light-emitting chip located in the bowl; and

d) at least one depression formed in a bottommost section of the bowl and receiving an adhesive therein, the at least one depression having an opening directed toward the chip, the opening having a diameter smaller than a bottom face of the chip, the adhesive filling the at least one depression and adhering the chip in the bowl,

wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board,

wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board, partially suspended and partially formed with columns which have column holes and are passed through the PC board.

33. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 23, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board, partially suspended and partially formed with columns which have column holes and are passed through the PC board.

Claims 34-35. (Canceled)

36. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

Claims 37-43. (Canceled)

44. (Original) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 32, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

Claim 45. (Canceled)

46. (New) A heat conductivity and brightness enhancing structure for light-emitting diode comprising: a bracket having:

a) a cathode leg support;

b) a bowl formed in an upper end of the cathode leg support;

c) a light-emitting chip located in the bowl; and

d) at least one depression formed in a bottommost section of the bowl and receiving an adhesive therein, the at least one depression having an opening directed toward the chip, the opening having a diameter smaller than a bottom face of the chip, the adhesive filling the at least one depression and adhering the chip in the bowl,

wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board, partially suspended and partially formed with columns which have column holes and are passed through the PC board.

47. (New) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 46, wherein the bowl has a recessed face having at least one step.

48. (New) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 46, wherein the circumference of the depression of the bowl is formed with concentric recesses.

49. (New) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 46, wherein at least one of the cathode leg support and anode leg support of the bracket is formed with heat-radiating wings.

50. (New) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 46, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

51. (New) The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 46, wherein a column hole is formed through the cathode leg support from at least one depression of the bowl to an outer side of the bracket.